

**JXP2N7002VRG**  
**N-CHANNEL ENHANCEMENT MODE MOSFET**

## DESCRIPTION

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## GENERAL FEATURES

- ◆  $V_{DS} = 60V, I_D = 0.3A$   
 $R_{DS(ON)} < 3\Omega @ V_{GS}=4.5V$   
 $R_{DS(ON)} < 2\Omega @ V_{GS}=10V$
- ◆ Dual N-Channel MOSFET
- ◆ Low On-Resistance
- ◆ Low Gate Threshold Voltage
- ◆ Low Input Capacitance
- ◆ Fast Switching Speed

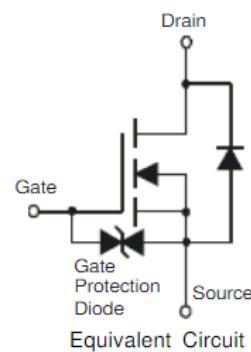
## APPLICATION

- ◆ PWM applications
- ◆ Load switch

## PACKAGE

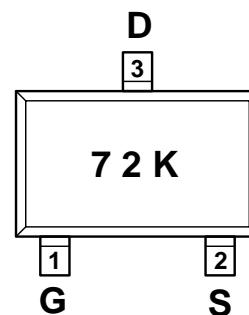
- ◆ SOT-23

## SCHEMATIC DIAGRAM



## PIN ASSIGNMENT

SOT-23  
(TOP VIEW)



## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Marking	Devices Per Reel
JXP2N7002VRG	-55°C to +150°C	SOT-23	72K	3000

## ABSOLUTE MAXIMUM RATINGS

( $T_A=25^\circ C$  unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	60	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current ( $T_J = 150^\circ C$ ) <sup>a</sup>	$I_D$	380	mA
		300	
Pulsed drain current <sup>b</sup>	$I_{DM}$	1200	
Continuous source current (diode conduction) <sup>a</sup>	$I_S$	380	
Power dissipation <sup>a</sup>	$P_D$	0.71	W
		0.46	
Operating junction and storage temperature range	$T_J, T_{stg}$	-55—150	°C

## THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Max	Unit
Maximum junction-to-ambient <sup>a</sup>	$R_{\theta JA}$	120	145	°C/W
Steady-State		140	175	
Maximum junction-to-foot	$R_{\theta JC}$	62	78	

Notes:

- a.  $TC = 25^{\circ}C$ .
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t = 5 \text{ s}$ .
- d. Maximum under steady state conditions is 400 °C/W.

## ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}C$ unless otherwise noted)

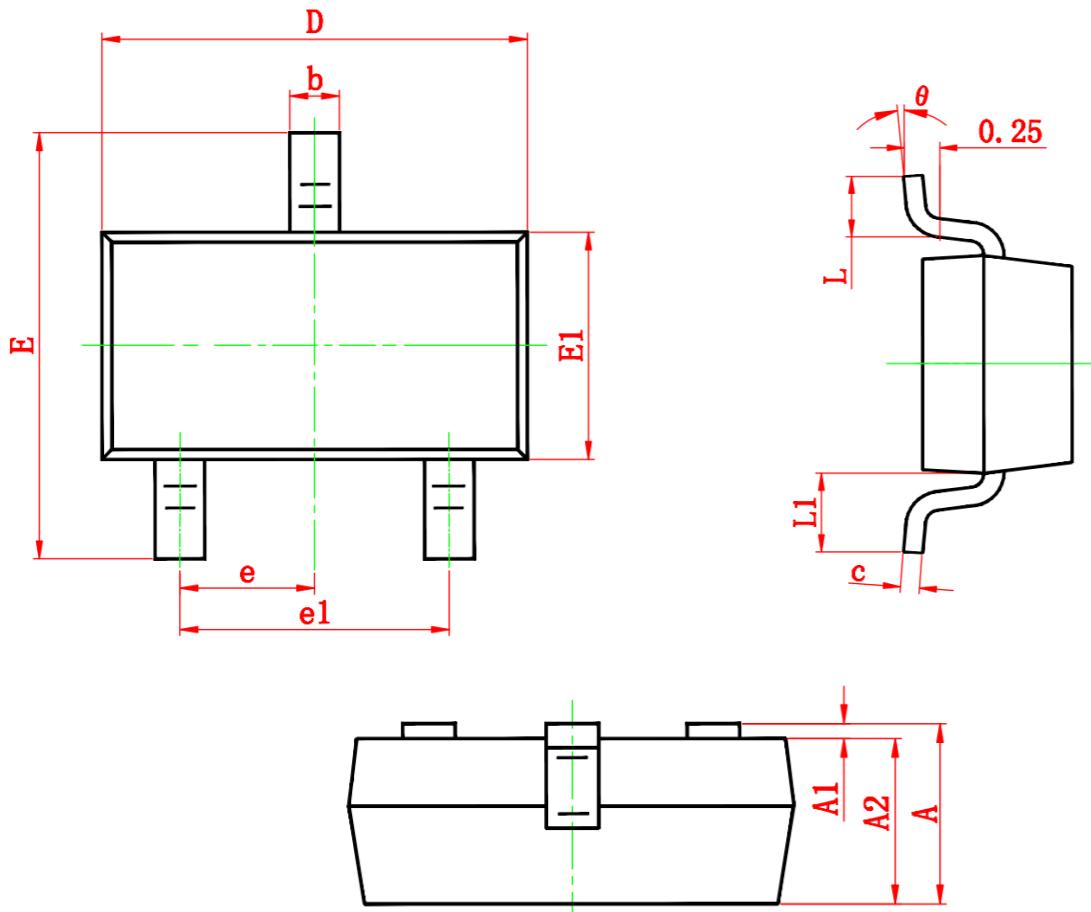
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	60	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 10$	$\mu A$
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.3	2.5	V
Drain-source on-state resistance <sup>a</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=0.34A$	-	0.9	2	$\Omega$
		$V_{GS}=4.5V, I_D=0.2A$	-	1.1	3	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS}=30V, I_D=0.2A$	-	159	-	ms
<b>Dynamic Characteristics <sup>b</sup></b>						
Input capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V$ $f=1.0MHz$	-	18.5	-	pF
Output capacitance	$C_{oss}$		-	7.5	-	
Reverse transfer capacitance	$C_{rss}$		-	4.2	-	
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(ON)}$	$V_{DD}=30V$ $I_D=0.3A$ $V_{GEN}=10V$ $R_L=100\Omega$ $R_{GEN}=1\Omega$	-	6.5	-	ns
Rise time	$tr$		-	12	-	
Turn-off delay time	$t_{D(OFF)}$		-	13	-	
Fall time	$tf$		-	14	-	
Total gate charge	$Q_g$		-	0.5	-	nC
Gate-source charge	$Q_{gs}$	$V_{DS}=30V, I_D=0.34A$ $V_{GS}=4.5V$	-	0.2	-	
Gate-drain charge	$Q_{gd}$		-	0.15	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	$V_{SD}$	$V_{GS}=0V, I_s=0.3A$	-	-0.81	-1.2	V

### Notes

- a. Pulse test: Pulse width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$
- b. Guaranteed by design, not subject to production testing

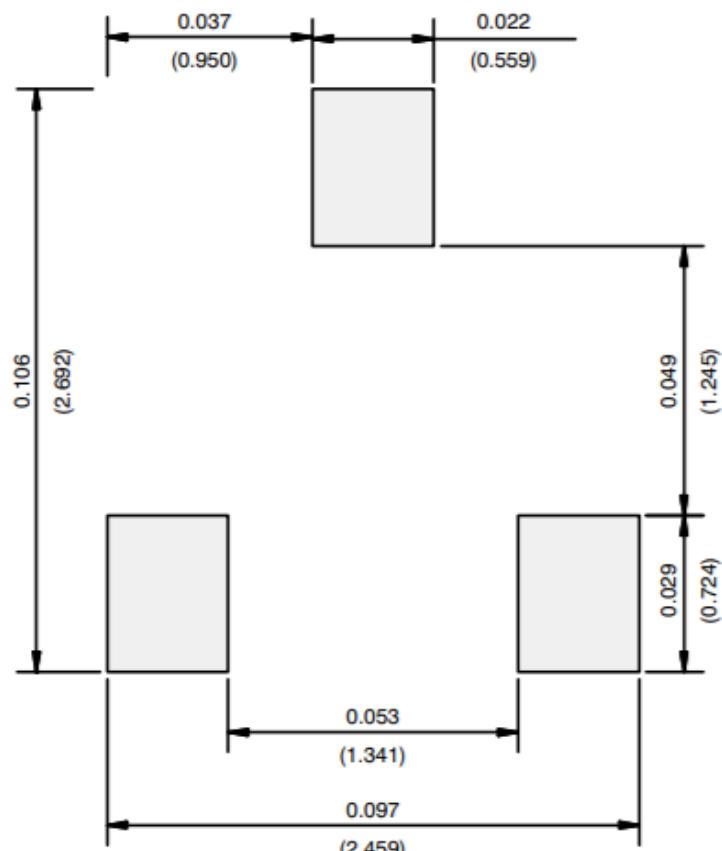
## PACKAGE INFORMATION

- SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
θ	0°	8°	0°	8°

## RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads  
Dimensions in Inches/(mm)